

Application Guide

INTRODUCTION:

Chomerics THERM-A-GAP™ T635 and T636 are the latest development in Chomerics fully cured, dispensable, form-in-place thermal gap filler products. These products are pre cured and require neither a mixing step nor a cure cycle. They are dispensed onto a component, the heat sink or chassis is assembled over the material, and the product is ready for shipment. The relative ease of application of these materials also makes them ideal for rework and field repair.

TYPICAL APPLICATIONS:

These materials require very low closure force to conform to highly variable surfaces so they are ideal for circuit boards where multiple packages of variable height have to be thermally connected to a heat sink or enclosure. They are ideally suited for filling gaps between .010 - .200 inches where their low deflection force will not place undue stresses on component leads or solder joints. T-635 and T636 can be applied to all commercially clean metal, ceramic and plastic surfaces. T635 and T636 do not slump or sag after being dispensed.

PACKAGING:

T635 and T636 are packaged in one of the following standard packages:

- 10 cc syringes - samples
- 30 cc syringes - small volume production, rework
- 180 cc cartridge
- 300 cc cartridge
- 360 cc cartridge

APPLICATION INSTRUCTIONS:

Surface Preparation:

T635 and T636 require no surface preparation before application as long as the surfaces are not visibly contaminated. If obvious contamination exists, remove the contaminant before applying the products.

Suggested Dispensing Equipment:

- 10 cc syringe - manual dispensing.
- 30 cc syringe - Semco Semmatic Series 1800, 1900 and 2000 time – pressure dispensers.
 - EFD Ultra 2400 positive displacement dispenser
- 180 and 360 cc cartridge - Semco Model 250 A sealant gun or equivalent.
 - EFD Ultra 2400 positive displacement dispenser
- 300 cc cartridge – Semco Model 550 sealant gun

